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PATENT ABSTRACTS OF JAPAN

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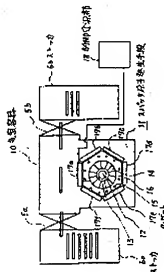
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(54) SPUTTERING DEVICE

(57)Abstract:

PURPOSE: To economize the space for equipment and also to prevent reduction in the rate of operation, by disposing plural targets in an airtight vessel in a sputtering device so that they form the prescribed angles and turning the targets at the prescribed position, and further, providing a means of conveying a substrate speed-controllably in forward and backward directions.

CONSTITUTION: A target 17a is turned so that it stands in parallel with a substrate and, in a state where the target is stopped, sputtering is applied to all substrates to form a thin film as a primary layer. Subsequently, a target 17b to be a secondary layer is turned at the prescribed angle and set up so that it stands in parallel with the substrate. After setting, the substrate on which the thin film as the primary layer is already formed and which is held in a stocker 5a is sent back to a stocker 5b at a conveyance speed suited for the target 17b to undergo sputtering, by which the secondary layer is formed. By this method, a multilayered film can be successively formed on the substrate.



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